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**VE320 – Summer 2021**

**Introduction to Semiconductor Devices**

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**Chapter 9 Metal-Semiconductor Schottky Junction**

# Outline

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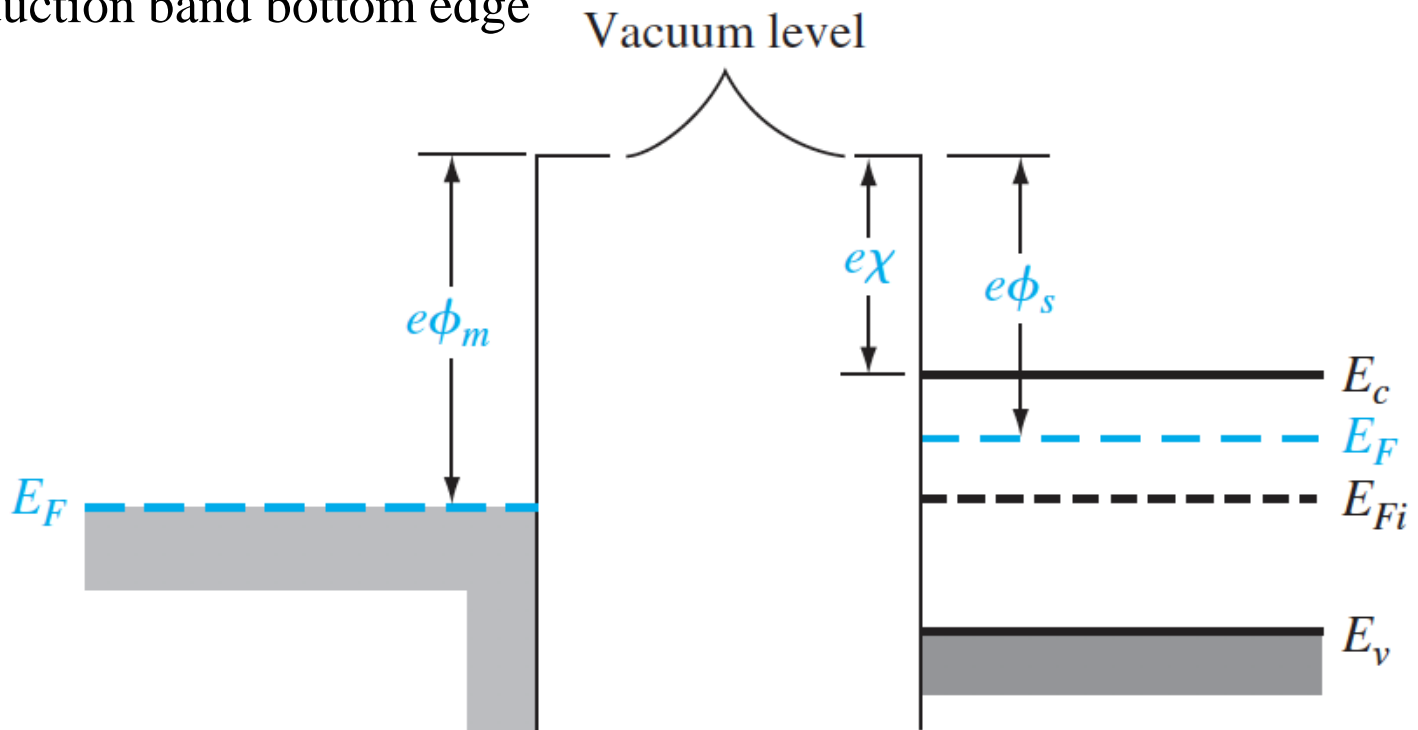
## **9.1 The Schottky barrier diode**

## 9.2 Metal-semiconductor Ohmic contacts

# 9.1 The Schottky barrier diode

## Qualitative characteristics

- Work function: energy difference between the vacuum energy level and the Fermi level
- Electron affinity: energy difference between the vacuum energy level and conduction band bottom edge



# 9.1 The Schottky barrier diode

## Qualitative characteristics

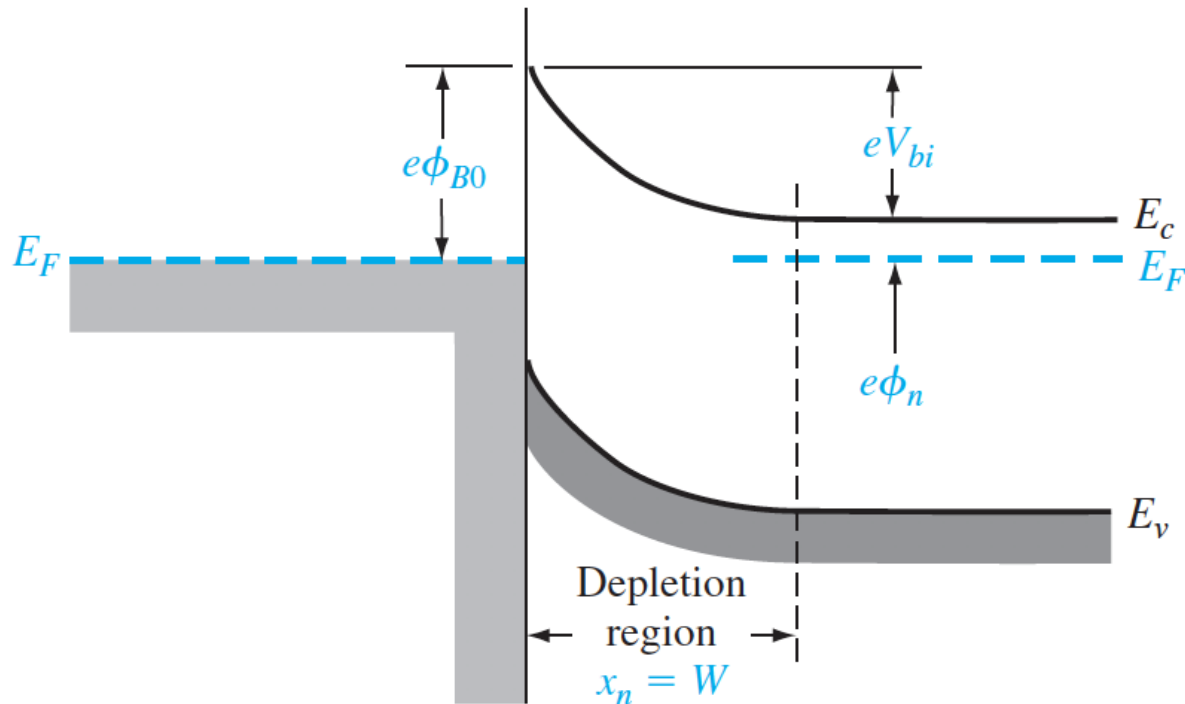
Element	Work function, $\phi_m$
Ag, silver	4.26
Al, aluminum	4.28
Au, gold	5.1
Cr, chromium	4.5
Mo, molybdenum	4.6
Ni, nickel	5.15
Pd, palladium	5.12
Pt, platinum	5.65
Ti, titanium	4.33
W, tungsten	4.55

Element	Electron affinity, $\chi$
Ge, germanium	4.13
Si, silicon	4.01
GaAs, gallium arsenide	4.07
AlAs, aluminum arsenide	3.5

# 9.1 The Schottky barrier diode

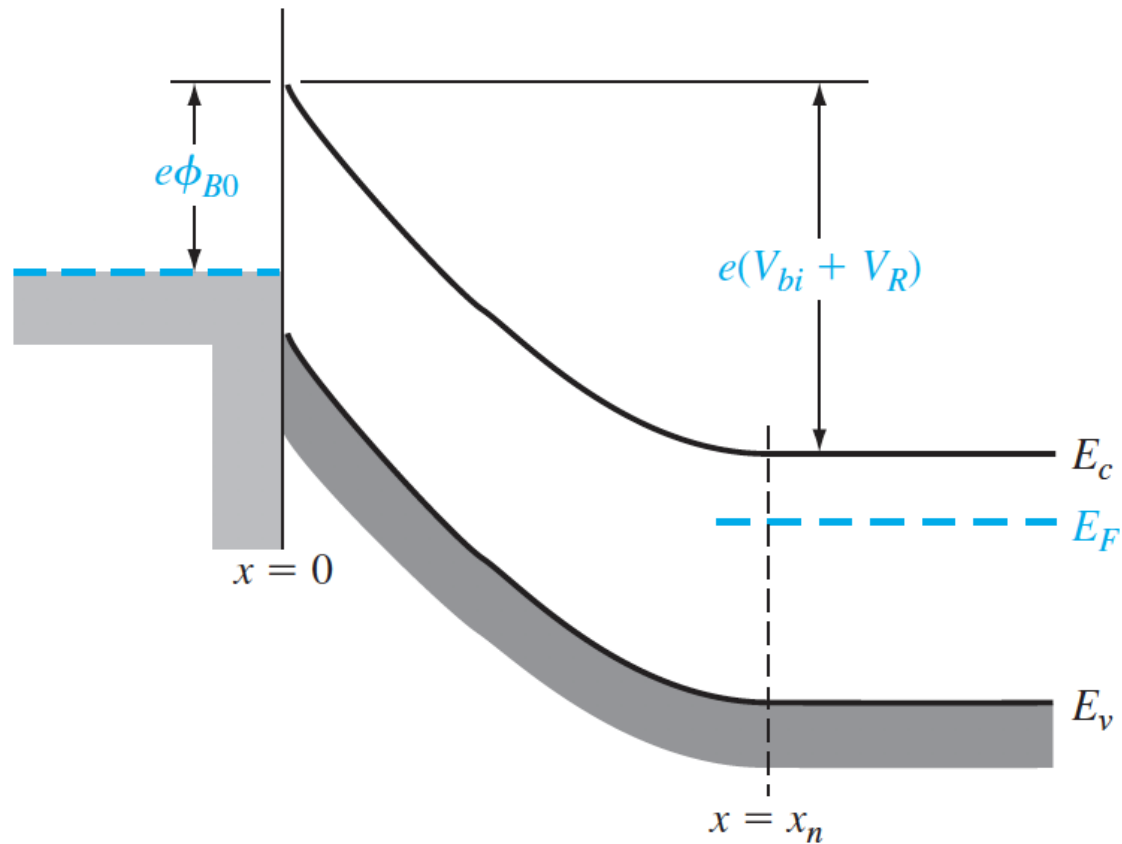
## Qualitative characteristics

- Schottky barrier:  $\phi_{B0} = (\phi_m - \chi)$
- Built-in potential barrier:  $V_{bi} = \phi_{B0} - \phi_n$



# 9.1 The Schottky barrier diode

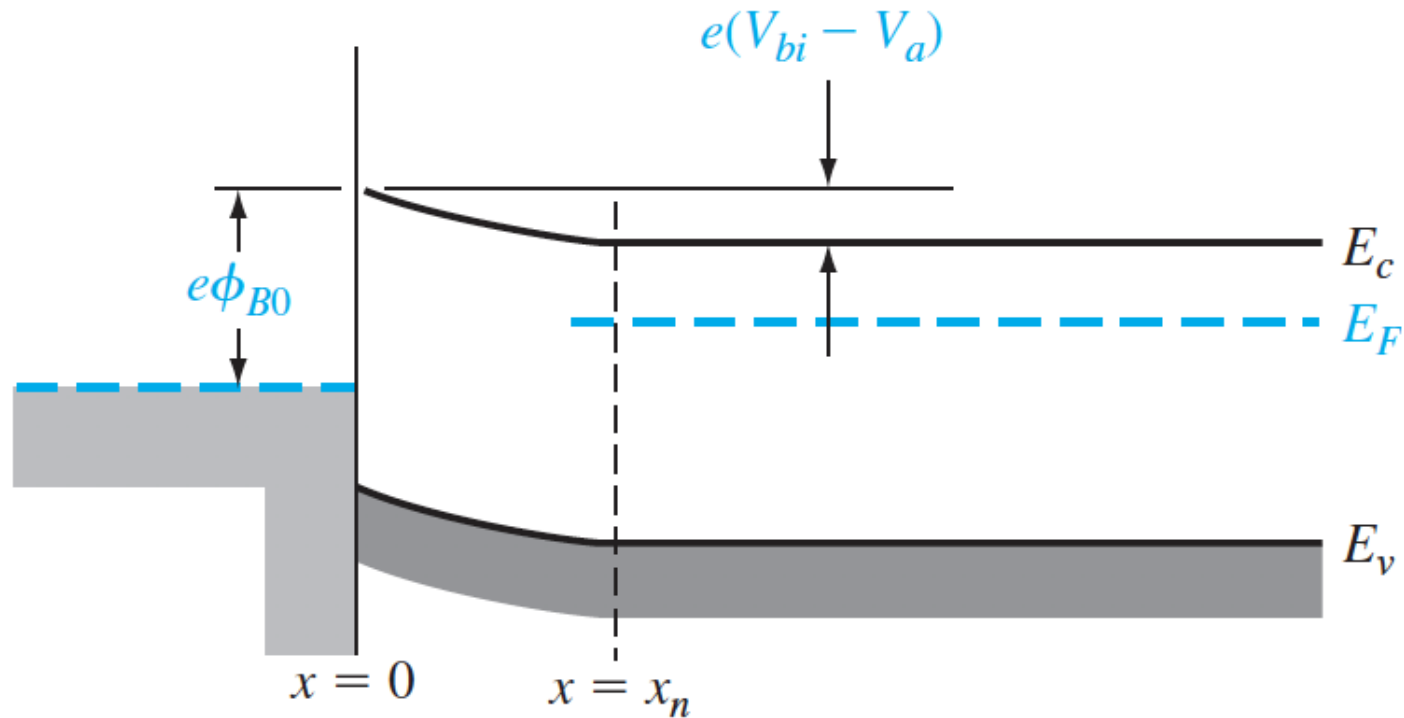
## Qualitative characteristics



Reverse bias

# 9.1 The Schottky barrier diode

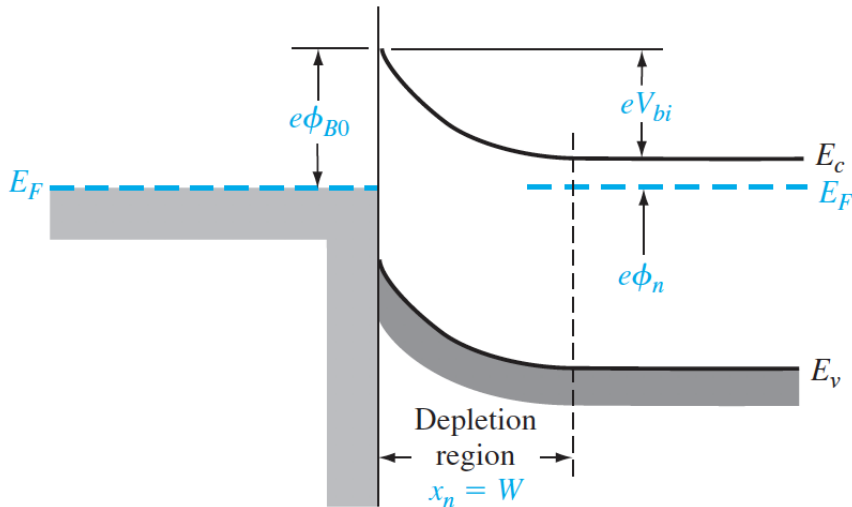
## Qualitative characteristics



Forward bias

# 9.1 The Schottky barrier diode

## Ideal junction properties



$$\frac{dE}{dx} = \frac{\rho(x)}{\epsilon_s}$$

$$E = \int \frac{eN_d}{\epsilon_s} dx = \frac{eN_dx}{\epsilon_s} + C_1$$

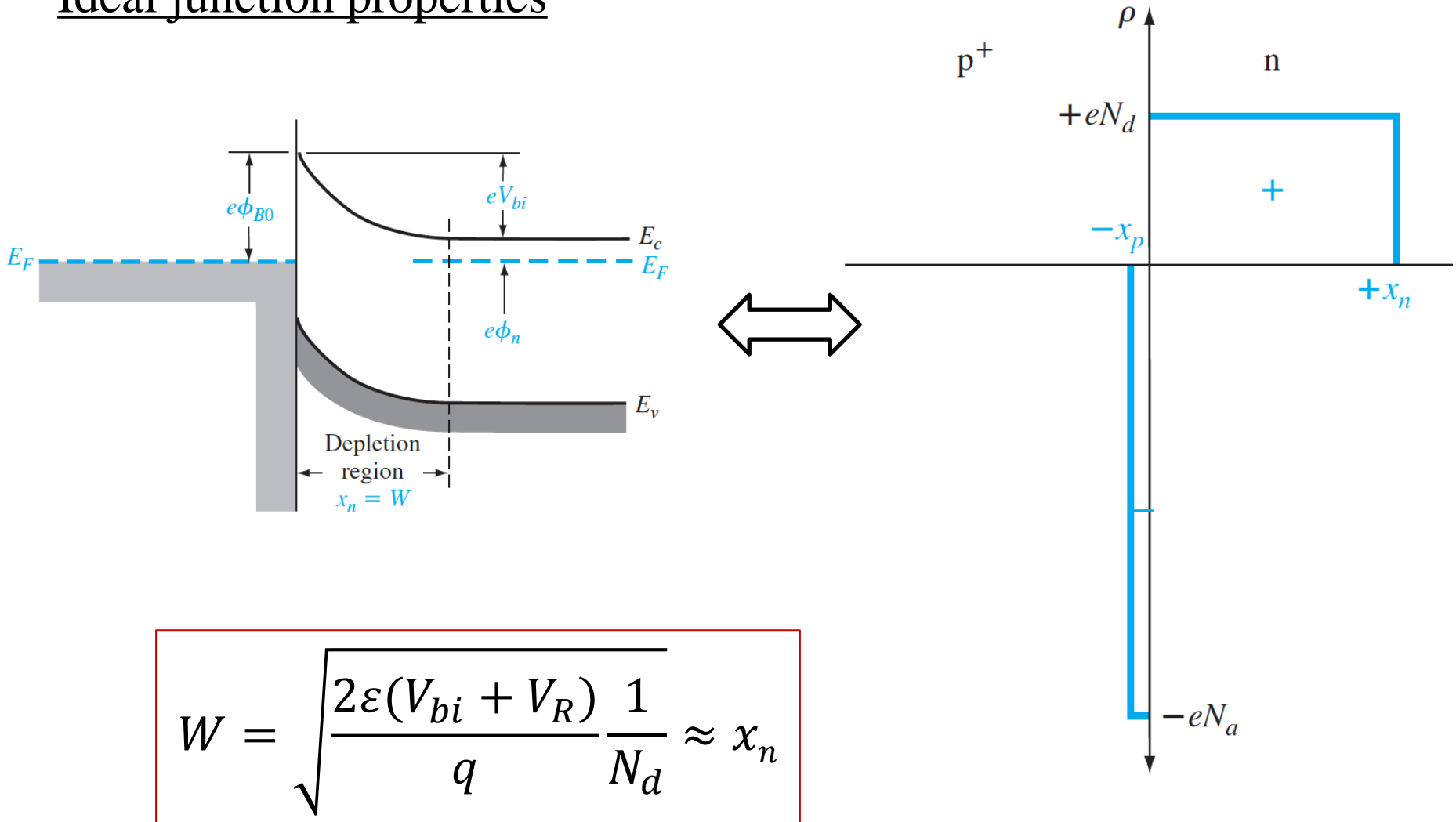
$$C_1 = -\frac{eN_dx_n}{\epsilon_s}$$

$$E = -\frac{eN_d}{\epsilon_s}(x_n - x)$$



# 9.1 The Schottky barrier diode

## Ideal junction properties



# 9.1 The Schottky barrier diode

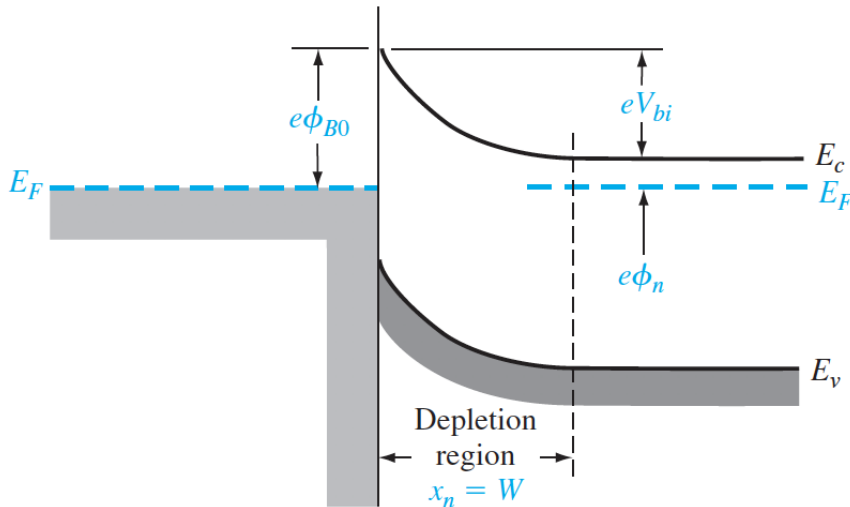
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## Problem Example #1

A metal-semiconductor junction is formed between a metal with a work function of 4.3 eV and p-type silicon with an electron affinity of 4.0 eV. The acceptor doping concentration in the silicon is  $N_a = 5 \times 10^{16} \text{ cm}^{-3}$ . Assume  $T = 300\text{K}$ . (a) Sketch the energy-band diagram. (b) Determine the height of the Schottky barrier. (c) Sketch the energy-band diagram with an applied reverse-biased voltage of  $V_R = 3\text{V}$ . (d) Sketch the energy-band diagram with applied forward-bias voltage of  $V_a = 0.25\text{V}$ . (15 points).

# 9.1 The Schottky barrier diode

## Ideal junction properties



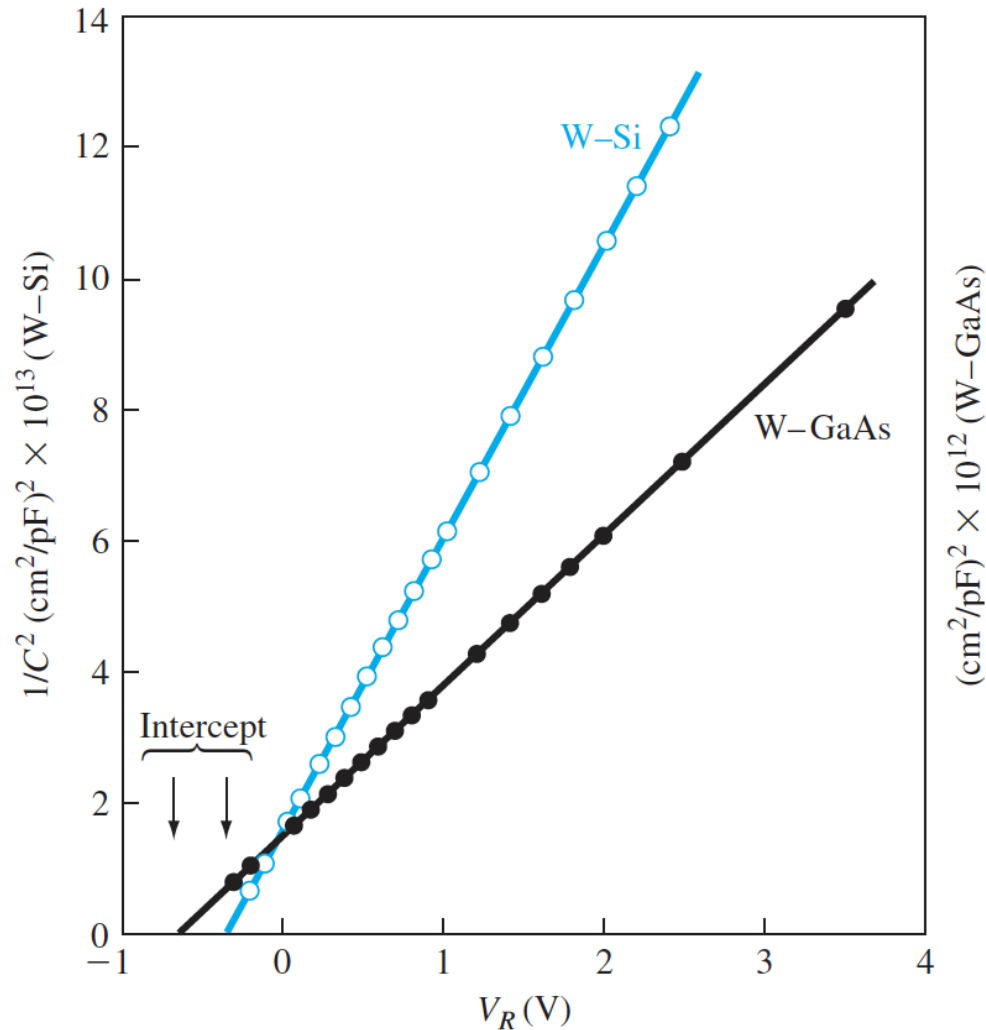
$$C' = C' = \frac{dQ}{dV_b} \big|_{V_b=V_0} = \frac{\varepsilon}{W} = \sqrt{\frac{q\varepsilon N_D}{2(V_{bi} + V_R)}}$$

$$\frac{1}{C'^2} = \frac{2(V_{bi} + V_R)}{q\varepsilon N_D}$$

$$W = \sqrt{\frac{2\varepsilon(V_{bi} + V_R)}{q}} \frac{1}{N_d} \approx x_n$$

# 9.1 The Schottky barrier diode

## Ideal junction properties



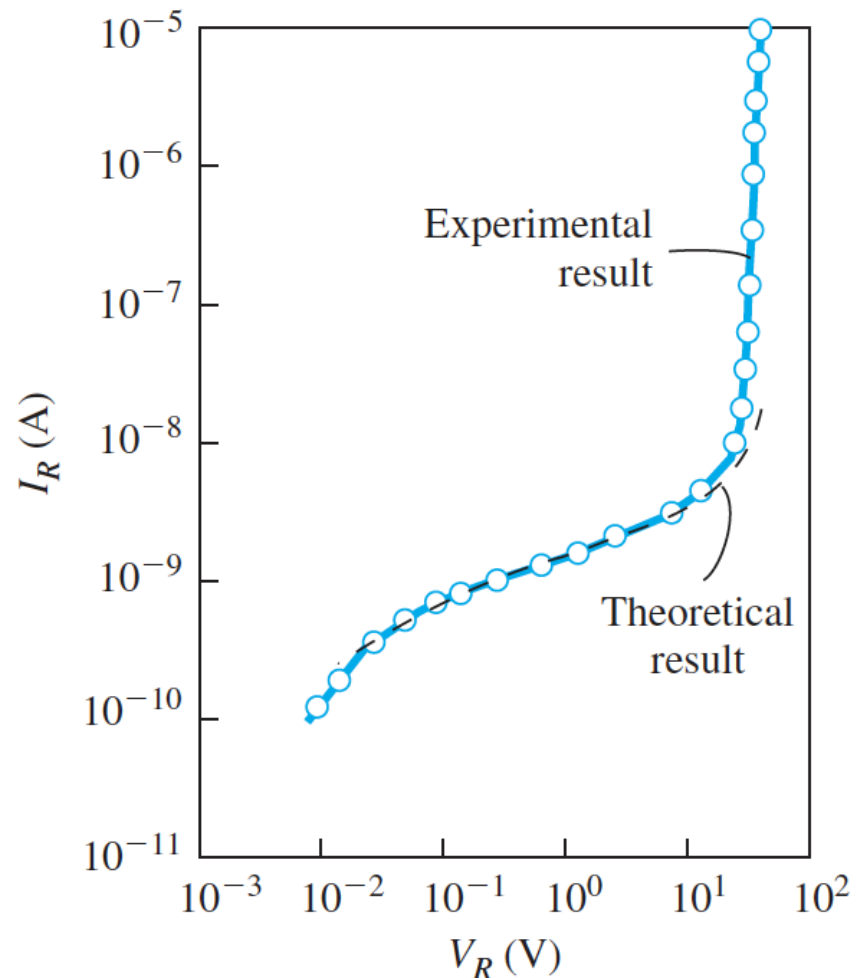
# 9.1 The Schottky barrier diode

## Current-voltage relationship

$$J = J_{sT} \left[ \exp \left( \frac{eV_a}{kT} \right) - 1 \right]$$

$$J_{sT} = A^* T^2 \exp \left( \frac{-e\phi_{Bn}}{kT} \right)$$

$$A^* \equiv \frac{4\pi e m_n^* k^2}{h^3}$$



$$J_{sT} = A^* T^2 \exp \left( \frac{-e\phi_{B0}}{kT} \right) \exp \left( \frac{e\Delta\phi}{kT} \right)$$

# 9.1 The Schottky barrier diode

## Current-voltage relationship

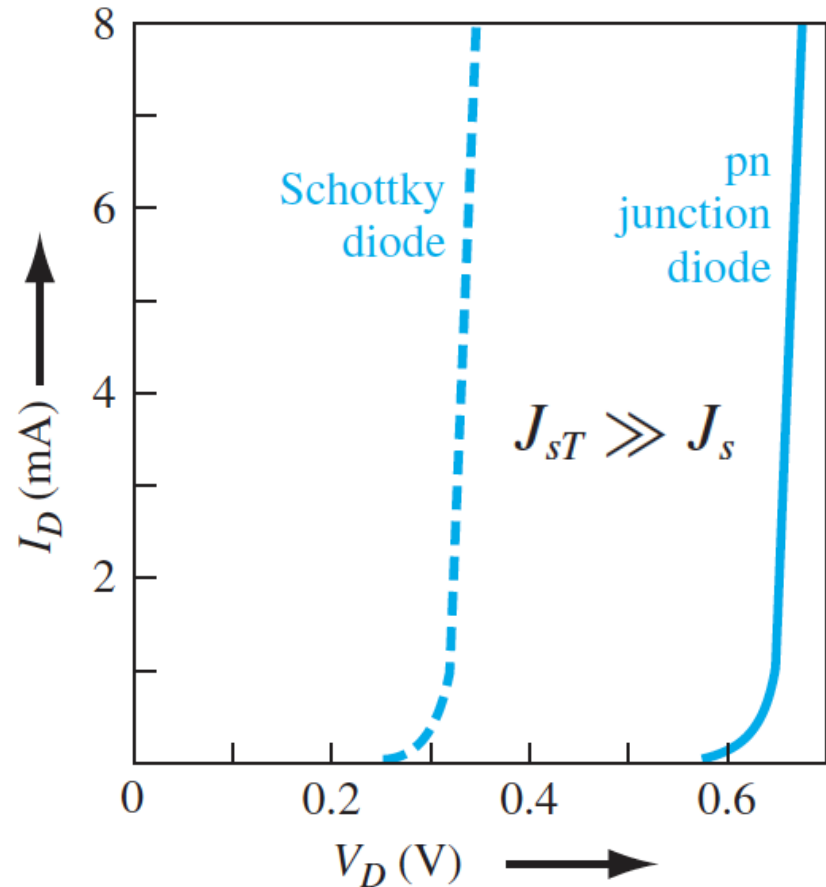
$$J = J_{sT} \left[ \exp \left( \frac{eV_a}{kT} \right) - 1 \right]$$

$$J_{sT} = A^* T^2 \exp \left( \frac{-e\phi_{Bn}}{kT} \right)$$

$$A^* \equiv \frac{4\pi e m_n^* k^2}{h^3}$$

Richardson constant

$$J_s = \frac{eD_n n_{po}}{L_n} + \frac{eD_p p_{no}}{L_p}$$



# Check your understanding

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## Problem example #2

Consider a tungsten barrier on silicon with a measured barrier height of  $\phi_{\text{Bn}} = 0.67\text{eV}$ . The effective Richardson constant is  $A^* = 114 \text{ A/K}^2\text{cm}^2$ .  $T = 300\text{K}$ .

# Check your understanding

## Problem example #3

### **Control of the Schottky Barrier Height in Monolayer WS<sub>2</sub> FETs using Molecular Doping**

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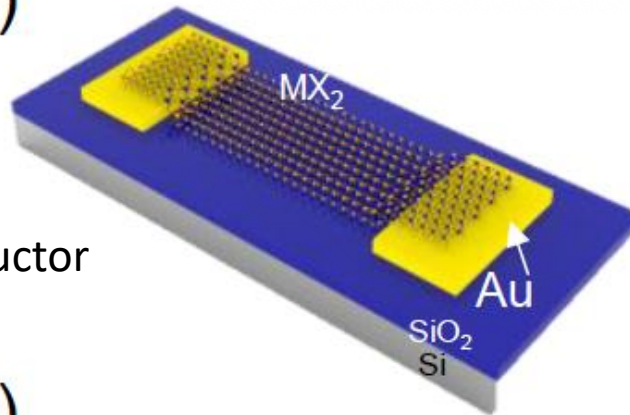


# Check your understanding

## Problem example #3

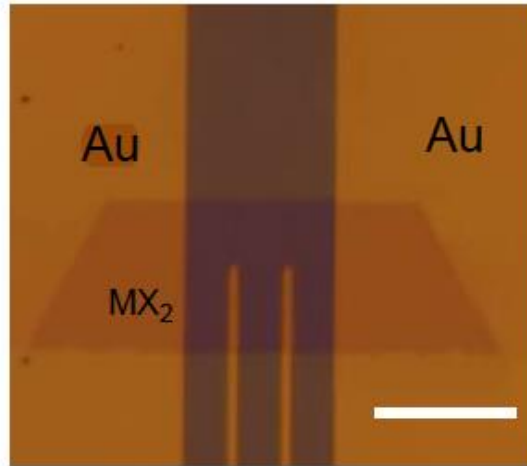
$$I_{sd} = AA_{2D}^* T^{3/2} \exp \left[ -\frac{q}{k_B T} \left( \Phi_B - \frac{V_{ds}}{n} \right) \right]$$

(a)



WS<sub>2</sub> atomically thin  
monolayer semiconductor

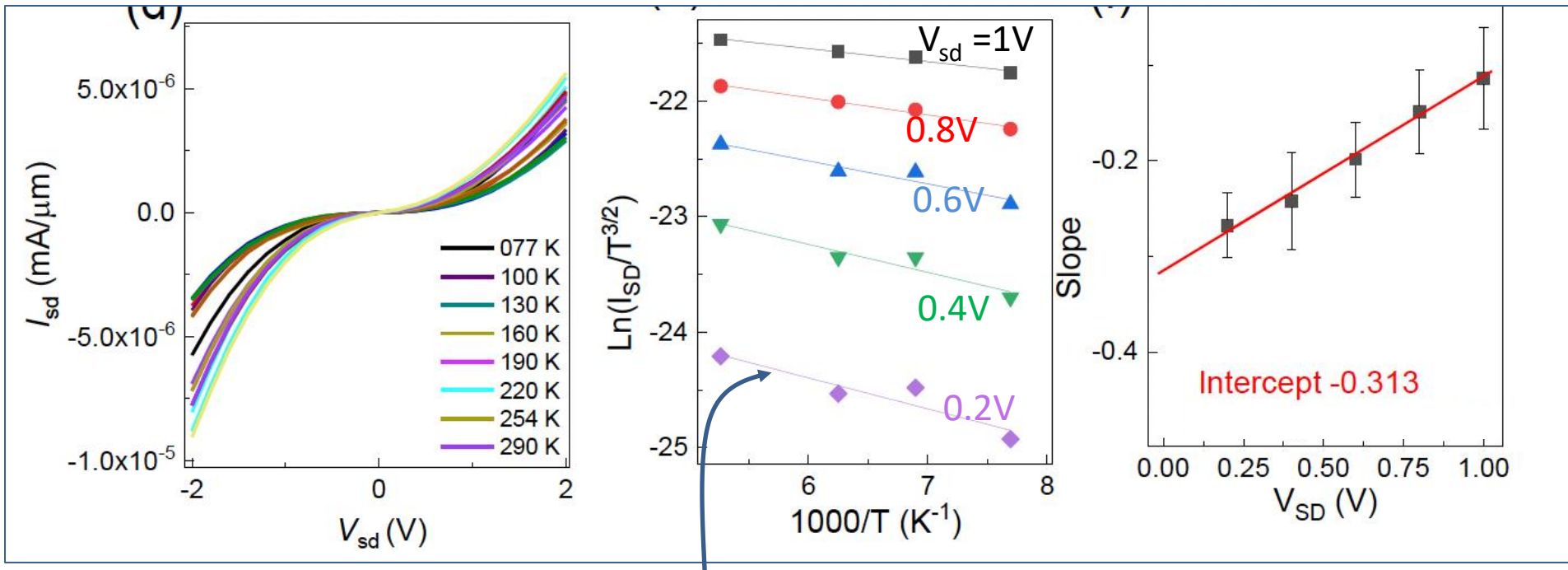
(b)



# Check your understanding

## Problem example #3

$$I_{sd} = AA_{2D}^* T^{3/2} \exp \left[ -\frac{q}{k_B T} \left( \Phi_B - \frac{V_{ds}}{n} \right) \right]$$



Line 1

- 1) Write the analytical expression of Line 1 if we take  $1000/T$  as  $x$  and  $\ln(I_{SD}/T^{3/2})$  as  $y$ ?
- 2) Write the expression of Slope in the right figure.
- 3) Find Schottky barrier height  $\Phi_B$

# Outline

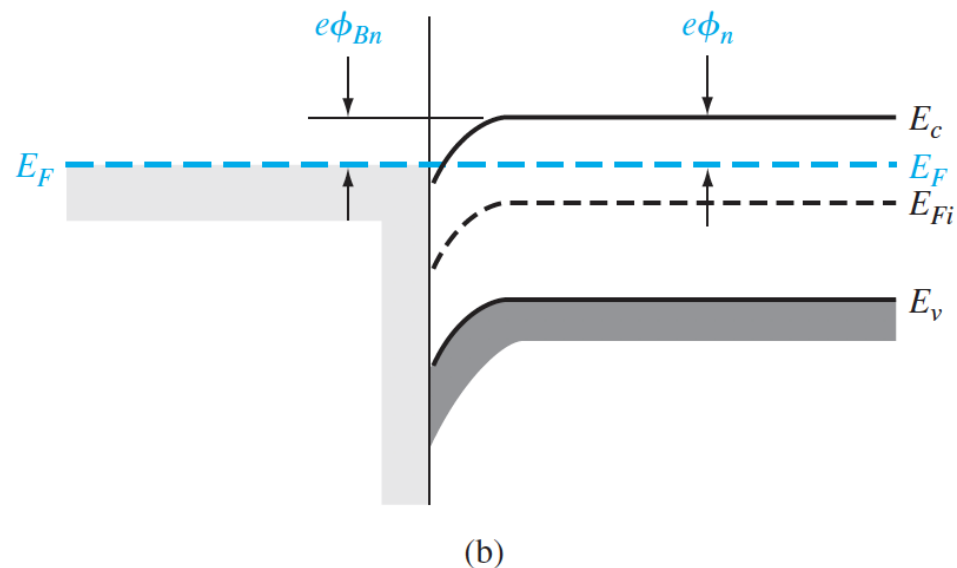
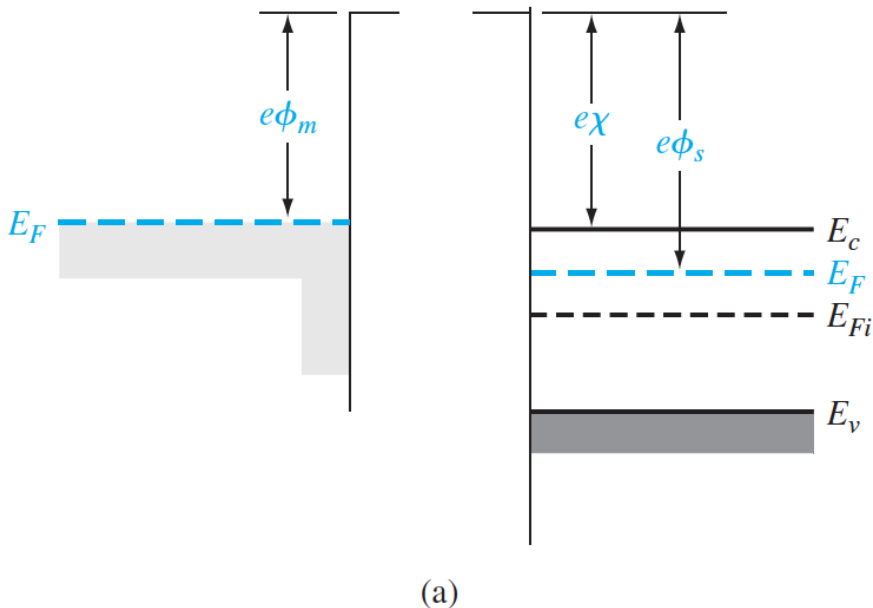
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9.1 The Schottky barrier diode

**9.2 Metal-semiconductor Ohmic contacts**

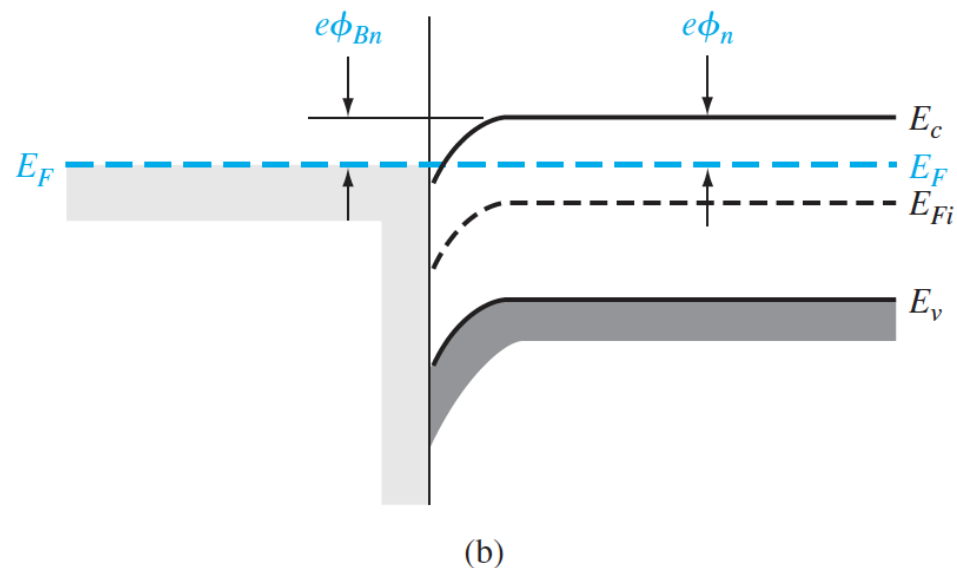
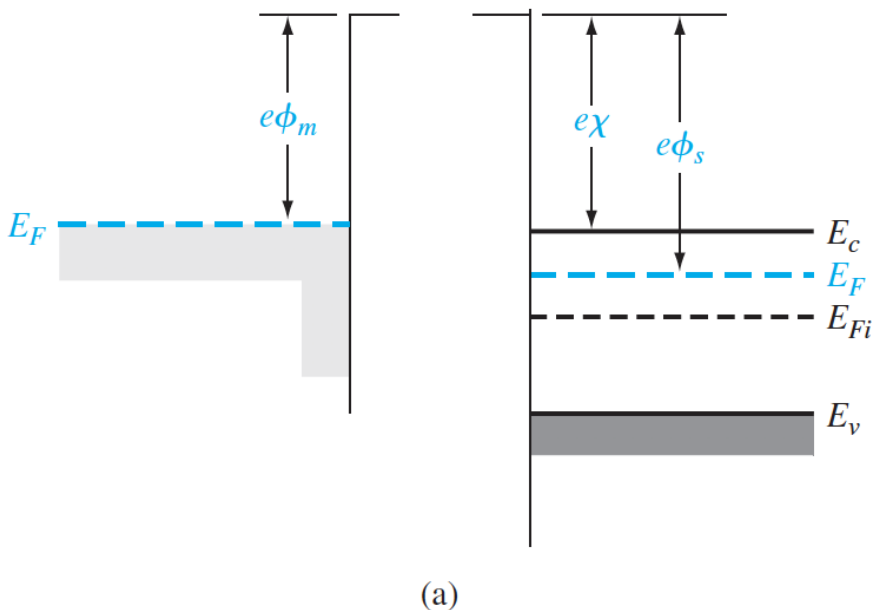
## 9.2 Metal-semiconductor Ohmic contacts

### Ideal Nonrectifying Barrier



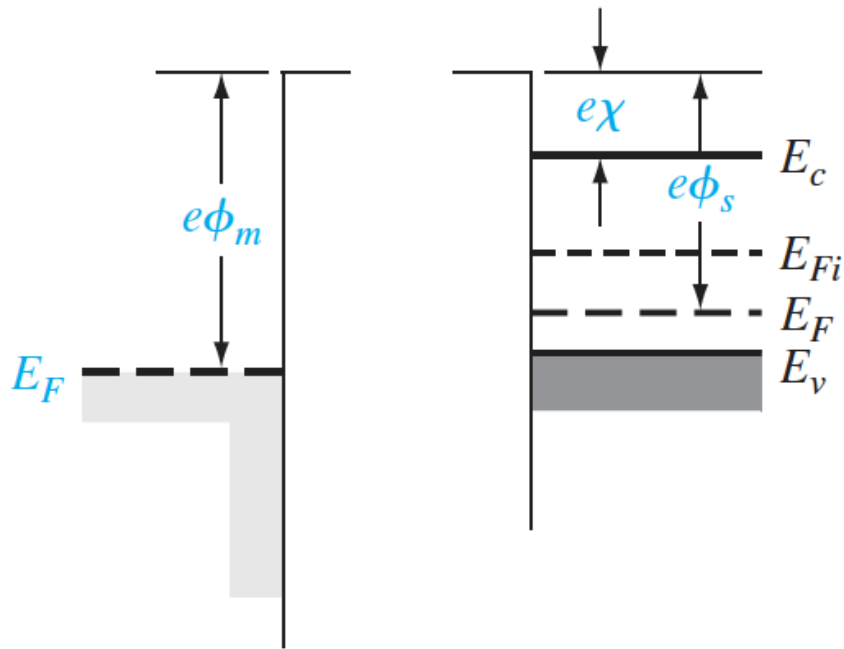
## 9.2 Metal-semiconductor Ohmic contacts

### Ideal Nonrectifying Barrier

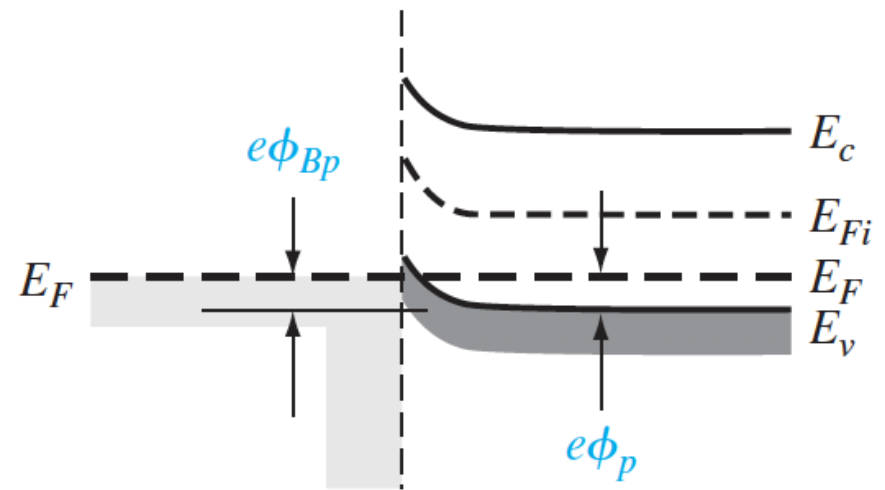


## 9.2 Metal-semiconductor Ohmic contacts

### Ideal Nonrectifying Barrier



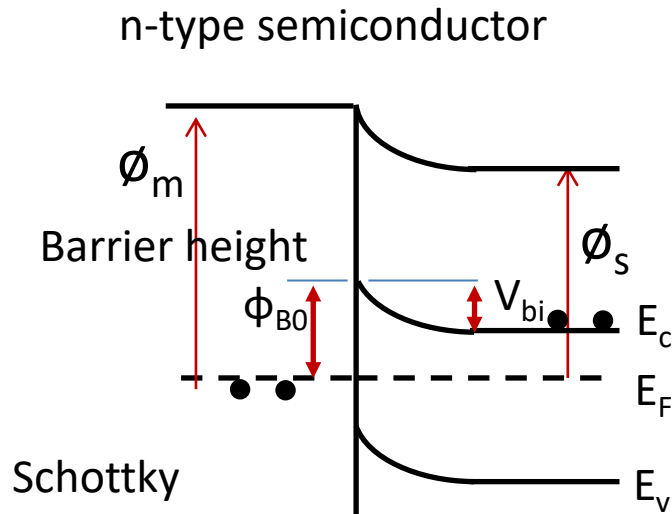
(a)



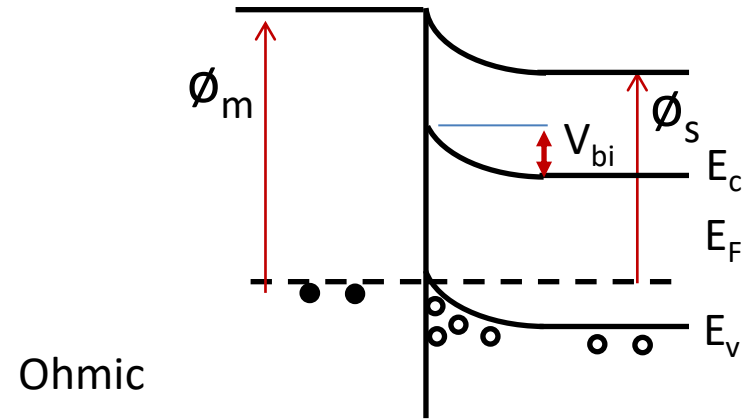
(b)

# 9.2 Metal-semiconductor Ohmic contacts

$$\phi_m > \phi_s$$

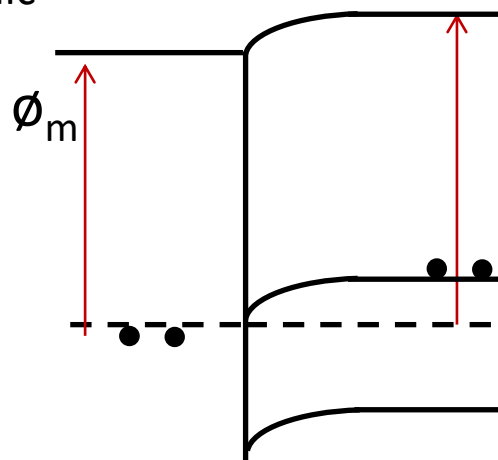


p-type semiconductor

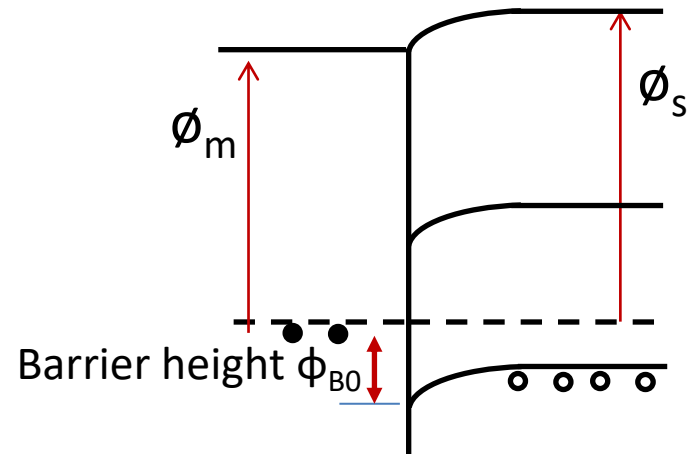


Ohmic

$$\phi_m < \phi_s$$



Schottky



# Check your understanding

## Problem example #4

For Si, if it is doped with phosphorus at a concentration of  $10^{15} \text{ cm}^{-3}$ , what metal you can choose from the list for Ohmic contact.

Repeat the question above for p-type Si doping at the concentration of  $10^{17} \text{ cm}^{-3}$ . Si has an electron affinity of 4.01 eV and a bandgap of 1.12 eV.

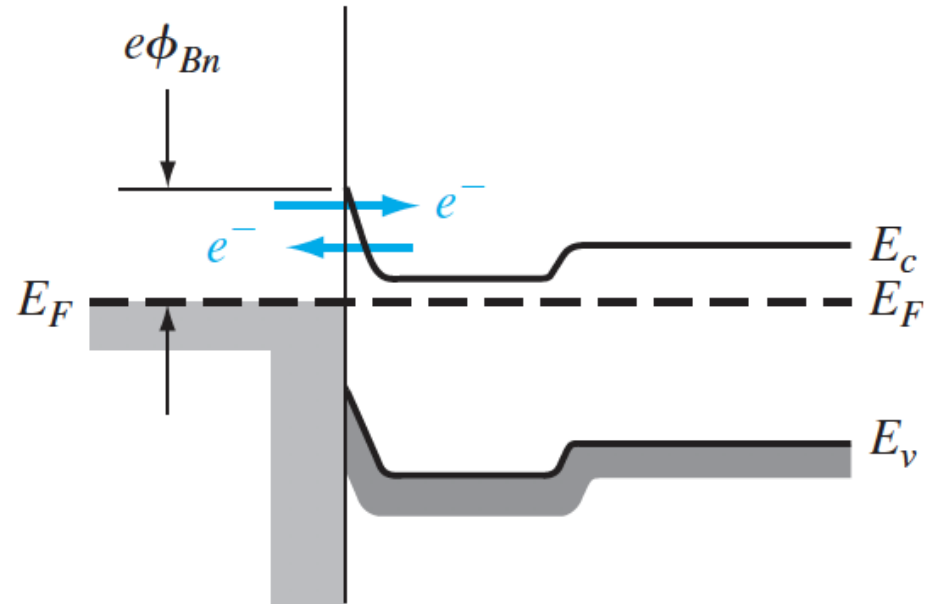
**Table 9.1** | Work functions of some elements

Element	Work function, $\phi_m$
Ag, silver	4.26
Al, aluminum	4.28
Au, gold	5.1
Cr, chromium	4.5
Mo, molybdenum	4.6
Ni, nickel	5.15
Pd, palladium	5.12
Pt, platinum	5.65
Ti, titanium	4.33
W, tungsten	4.55



## 9.2 Metal-semiconductor Ohmic contacts

### Tunneling Barrier



The tunneling current has the form

$$J_t \propto \exp\left(\frac{-e\phi_{Bn}}{E_{oo}}\right)$$

where

$$E_{oo} = \frac{e\hbar}{2} \sqrt{\frac{N_d}{\epsilon_s m_n^*}}$$

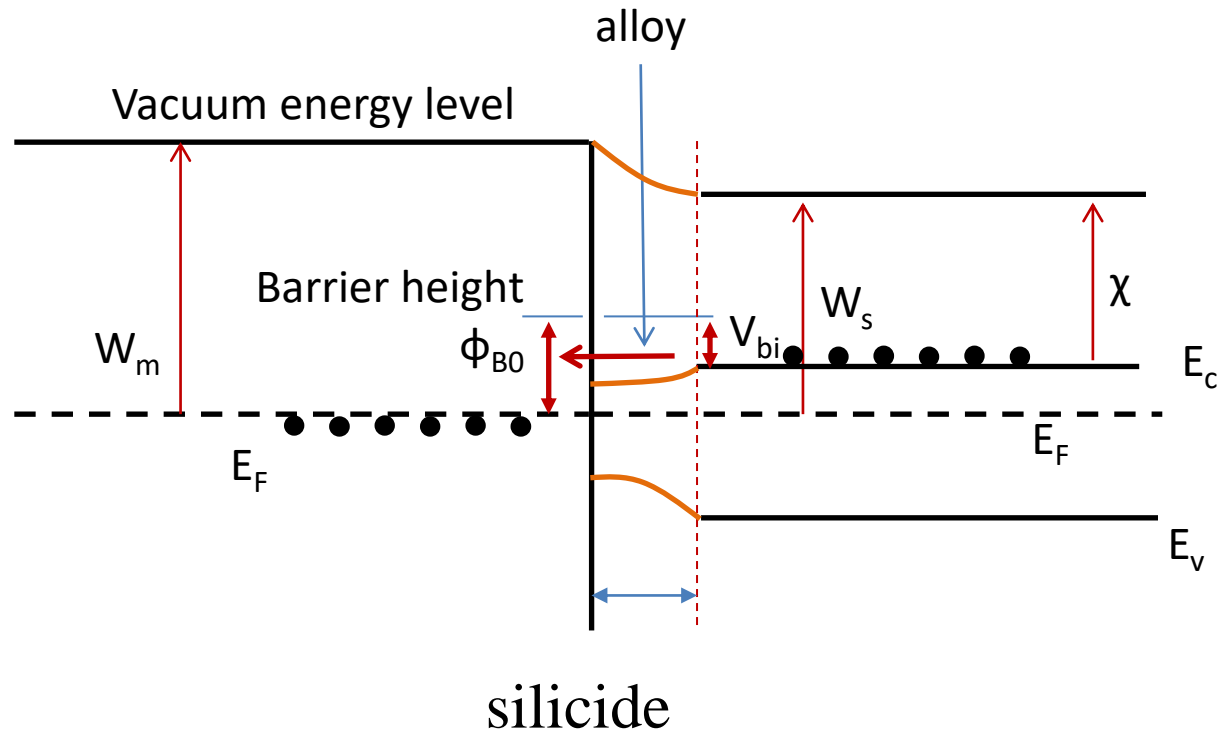
The tunneling current increases exponentially with doping concentration.

## 9.2 Metal-semiconductor Ohmic contacts

Silicide alloy

Nickel silicide, NiSi

Titanium silicide, TiSi<sub>2</sub>



## 9.2 Metal-semiconductor Ohmic contacts

### Specific contact resistance

$$R_c = \left( \frac{\partial J}{\partial V} \right)^{-1} \bigg|_{V=0} \quad \Omega\text{-cm}^2$$

$$J_n = A^* T^2 \exp\left(\frac{-e\phi_{Bn}}{kT}\right) \left[ \exp\left(\frac{eV}{kT}\right) - 1 \right]$$

$$R_c = \frac{\left(\frac{kT}{e}\right) \exp\left(\frac{+e\phi_{Bn}}{kT}\right)}{A^* T^2}$$

